

1. General description

Dual common cathode power Schottky diode designed for high frequency switched mode power supplies in a TO220 plastic package.



2. Features and benefits

- Trench structure
- High junction temperature up to 150 °C
- Low forward voltage drop, negligible switching losses
- High efficiency

3. Applications

- DC to DC converters
- Freewheeling diode
- OR-ing diode
- Switched mode power supply rectifier

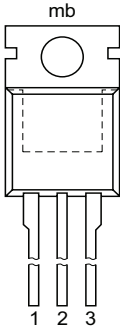
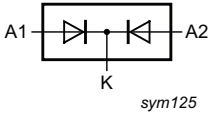
4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Notes	Values			Unit
Absolute maximum rating							
V _{RRM}	repetitive peak reverse voltage			45			V
I _{F(AV)}	average forward current	δ = 0.5 ; square-wave pulse; T _{mb} ≤ 132 °C; per diode; Fig. 1 ; Fig. 2 ; Fig. 3		15			A
I _{O(AV)}	average output current	δ = 0.5 ; square-wave pulse; T _{mb} ≤ 133 °C; both diodes conducting		30			A
Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
Static characteristics							
V _F	forward voltage	I _F = 15 A; T _J = 25 °C; per diode; Fig. 6		-	0.50	0.60	V
I _R	reverse current	V _R = 45 V; T _J = 25 °C; per diode; Fig. 7 ; Fig. 8		-	40	100	μA

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	A1	anode 1		
2	K	cathode		
3	A2	anode 2		
mb	K	mounting base; connected to cathode		

6. Ordering information

Table 3. Ordering information

Type number	Package name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
WN3S30H45C	TO220	WN3S30H45CQ	Tube	50	SOT78	13-Jun-2008

7. Marking

Table 4. Marking codes

Type number	Marking codes
WN3S30H45C	WN3S30 H45C

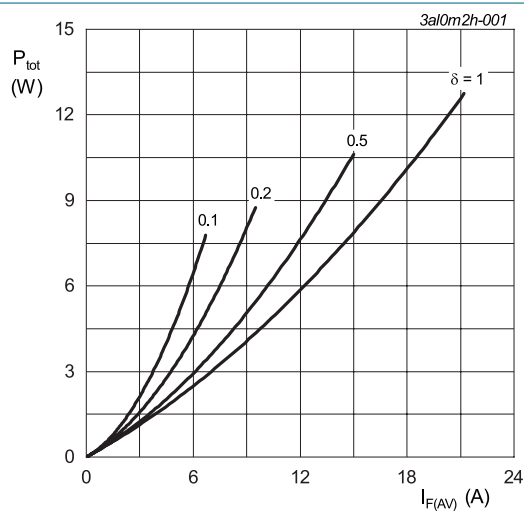
8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Notes	Values	Unit
V_{RRM}	repetitive peak reverse voltage			45	V
V_{RWM}	crest working reverse voltage			45	V
V_R	reverse voltage	DC		45	V
$I_{F(AV)}$	average forward current	$\delta = 0.5$; square-wave pulse; $T_{mb} \leq 132\text{ }^{\circ}\text{C}$; per diode; Fig. 1 ; Fig. 2 ; Fig. 3		15	A
$I_{O(AV)}$	average output current	$\delta = 0.5$; square-wave pulse; $T_{mb} \leq 133\text{ }^{\circ}\text{C}$; both diodes conducting		30	A
I_{FSM}	non-repetitive peak forward current	$t_p = 10\text{ ms}$; $T_{j(\text{init})} = 25\text{ }^{\circ}\text{C}$; sine-wave pulse; per diode; Fig. 4		250	A
		$t_p = 8.3\text{ ms}$; $T_{j(\text{init})} = 25\text{ }^{\circ}\text{C}$; sine-wave pulse; per diode		275	A
T_{stg}	storage temperature			-40 to 150	$^{\circ}\text{C}$
T_j	junction temperature		[1]	-40 to 150	$^{\circ}\text{C}$

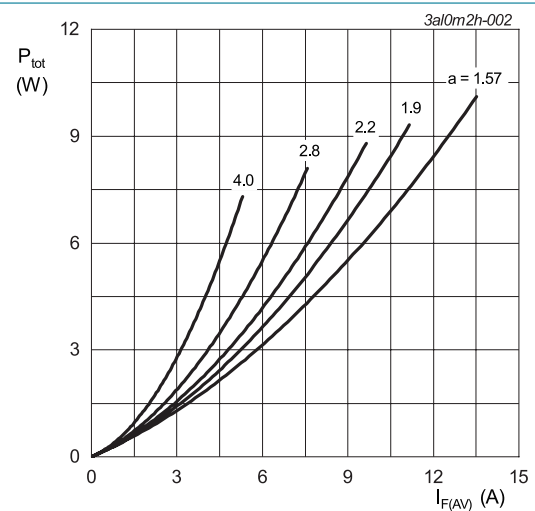
[1] The heat generated must be less than the thermal conductivity from Junction to Ambient: $dP_{tot}/dT_j < 1/R_{th(j-a)}$



$$I_{F(AV)} = I_{F(RMS)} \times \sqrt{\delta}$$

$$V_o = 0.341\text{ V}; R_s = 0.0122\text{ }\Omega$$

Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values; per diode



$$a = \text{form factor} = I_{F(RMS)} / I_{F(AV)}$$

$$V_o = 0.341\text{ V}; R_s = 0.0122\text{ }\Omega$$

Fig. 2. Forward power dissipation as a function of average forward current; sinusoidal waveform; maximum values; per diode

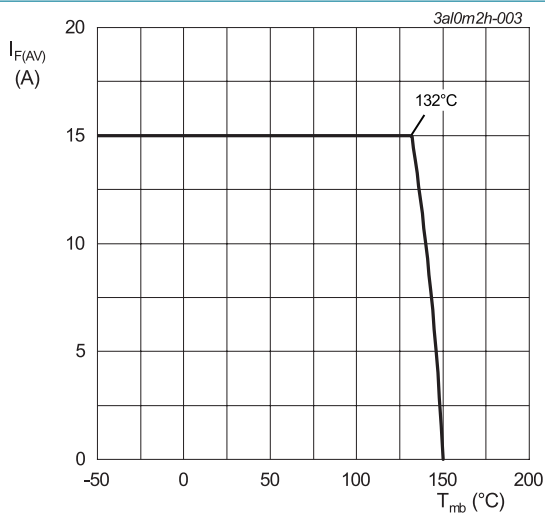


Fig. 3. Average forward current as a function of mounting base temperature; maximum values; per diode

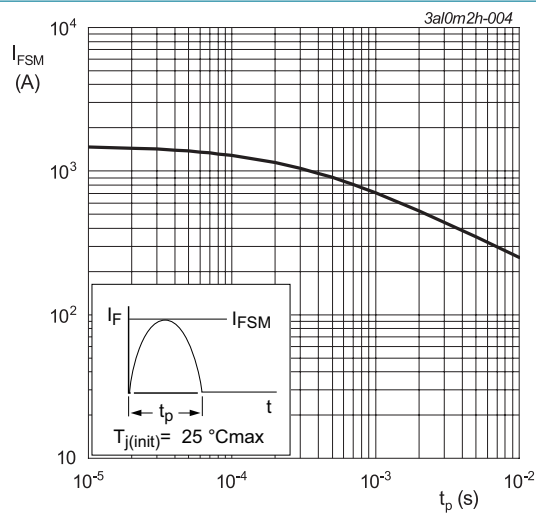
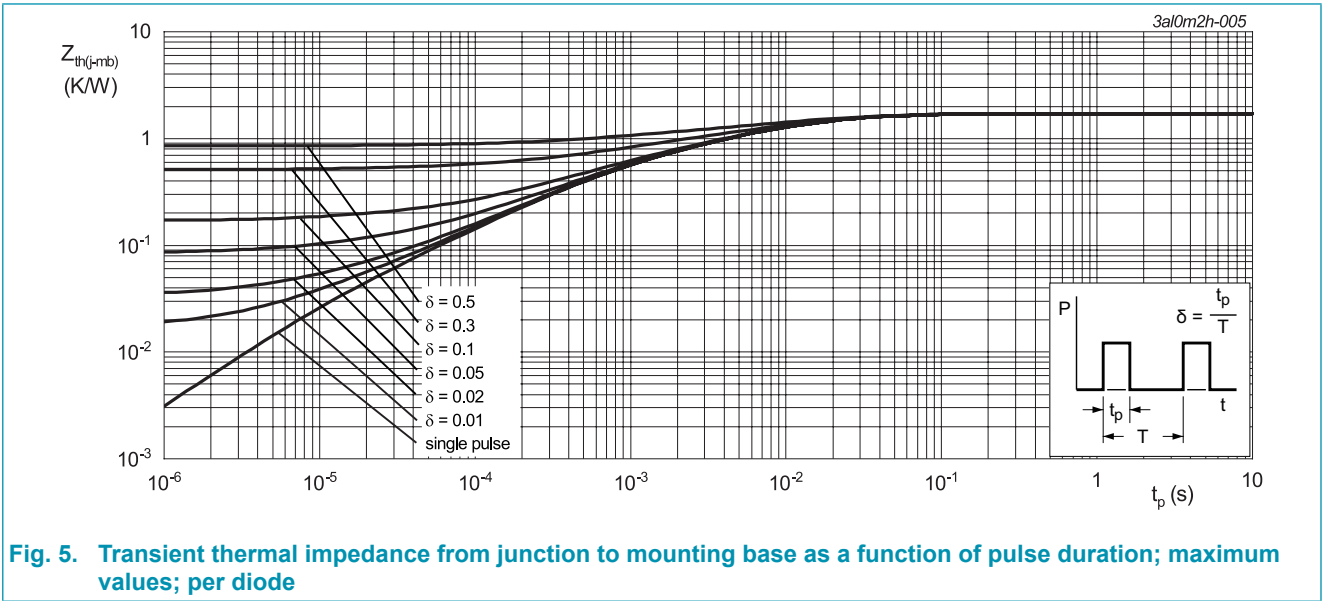


Fig. 4. Non-repetitive peak forward current as a function of pulse width; sinusoidal waveform; maximum values; per diode

9. Thermal characteristics

Table 6. Thermal characteristics

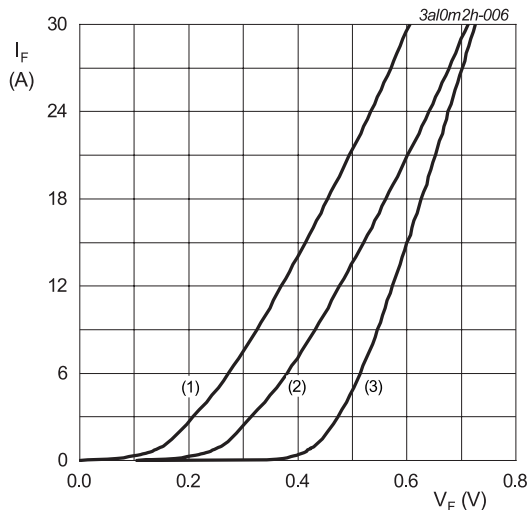
Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	per diode; Fig. 5		-	-	1.7	K/W
		both diodes conducting		-	-	0.8	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air		-	60	-	K/W



10. Characteristics

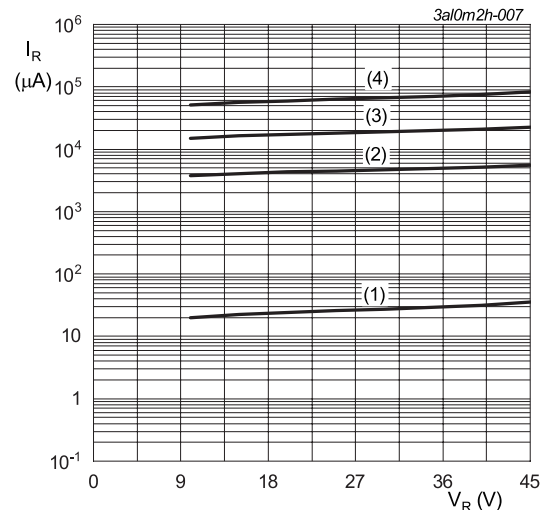
Table 7. Characteristics

Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
Static characteristics							
V_F	forward voltage	$I_F = 15\text{ A}$; $T_J = 25\text{ °C}$; per diode; Fig. 6		-	0.50	0.60	V
		$I_F = 15\text{ A}$; $T_J = 125\text{ °C}$; per diode; Fig. 6		-	0.44	-	V
		$I_F = 5\text{ A}$; $T_J = 25\text{ °C}$; per diode; Fig. 6		-	0.40	-	V
		$I_F = 5\text{ A}$; $T_J = 125\text{ °C}$; per diode; Fig. 6		-	0.29	-	V
I_R	reverse current	$V_R = 45\text{ V}$; $T_J = 25\text{ °C}$; per diode; Fig. 7 ; Fig. 8		-	40	100	μA
		$V_R = 45\text{ V}$; $T_J = 125\text{ °C}$; per diode; Fig. 7 ; Fig. 8		-	25	75	mA



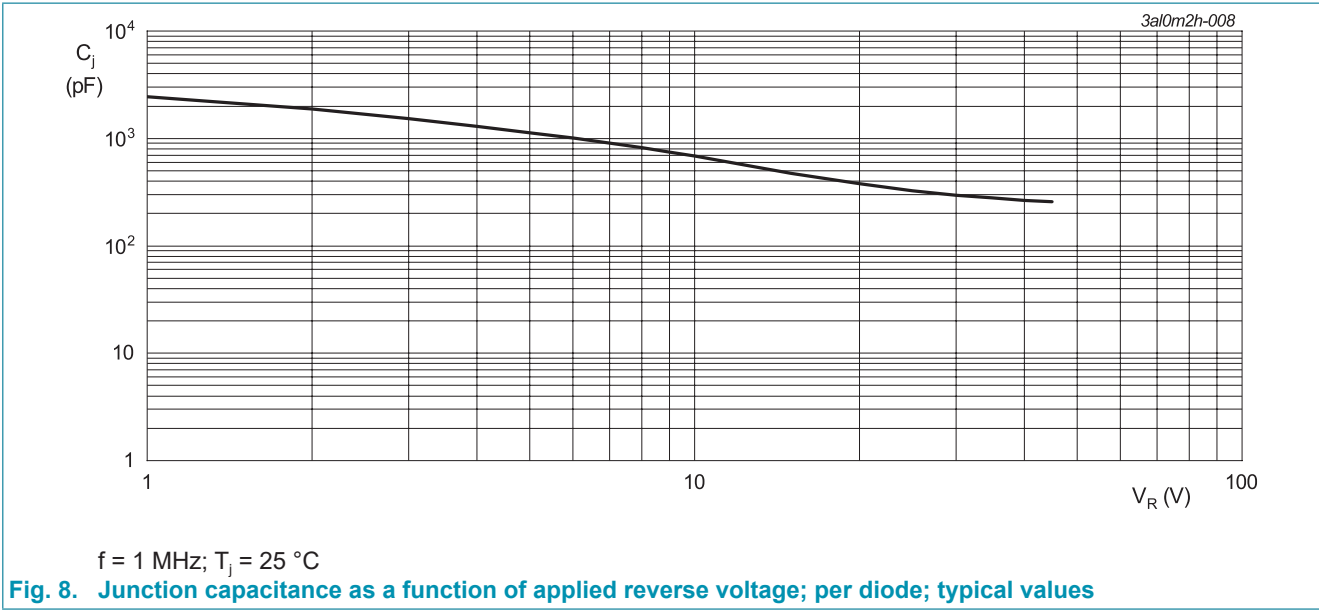
$V_o = 0.341\text{ V}$; $R_s = 0.0122\text{ }\Omega$
 (1) $T_J = 150\text{ °C}$; typical values
 (2) $T_J = 150\text{ °C}$; maximum values
 (3) $T_J = 25\text{ °C}$; maximum values

Fig. 6. Forward current as a function of forward voltage; per diode



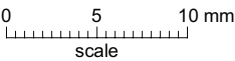
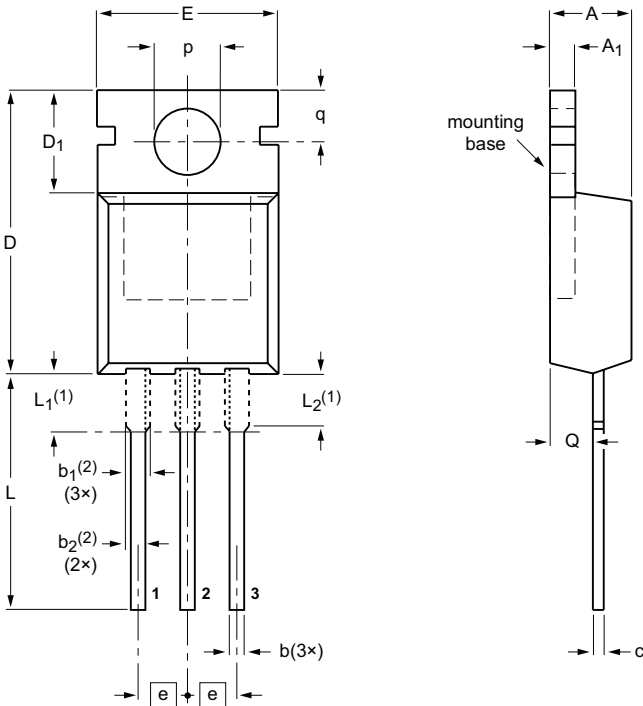
(1) $T_J = 25\text{ °C}$; typical values
 (2) $T_J = 100\text{ °C}$; typical values
 (3) $T_J = 125\text{ °C}$; typical values
 (4) $T_J = 150\text{ °C}$; typical values

Fig. 7. Reverse leakage current as a function of reverse voltage; per diode; typical values



11. Package outline

Plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO-220AB SOT78



DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₁	b	b ₁ (2)	b ₂ (2)	c	D	D ₁	E	e	L	L ₁ (1)	L ₂ (1) max.	p	q	Q
mm	4.7 4.1	1.40 1.25	0.9 0.6	1.6 1.0	1.3 1.0	0.7 0.4	16.0 15.2	6.6 5.9	10.3 9.7	2.54	15.0 12.8	3.30 2.79	3.0	3.8 3.5	3.0 2.7	2.6 2.2

- Notes
1. Lead shoulder designs may vary.
 2. Dimension includes excess dambar.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT78		3-lead TO-220AB	SC-46			08-04-23 08-06-13

12. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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- [2] The term 'short data sheet' is explained in section "Definitions".
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Date of release: 30 August 2022